

Program No.	Session Subtitle	Title	First author	affiliation
P-11	Surface Reaction and Etching Technology	The enhancement factors of substrate oxidation in O ₂ /FG ashing process	Masaaki Shinohara	Renesas Electronics Corp.
P-12		Surface treatment and characterization of ITO thin films using cyclonic atmospheric pressure plasma	Chun Huang	Yuan Ze Univ.
P-13		Plasma exposure effect on nanoporous SiCOH dielectric films at an argon plasma	B. H. Moon	Kyungshung Univ.
P-14		Highly selective etching of gap-fill dielectrics over SiC and SiN by the dc-bias superposed dual-frequency CCP	Tatsuya Komuro	Nagoya Univ.
P-15		Microfabrication of Silicon by Reactive Ion Etching Using CO ₂ Plasma	Akihiro Matsutani	Tokyo Tech
P-16		Quantum chemical investigations for excitation dissociations of C ₅ F ₈ and C ₅ H ₇ etching gases	Toshio Hayashi	Nagoya Univ.
P-17		A reduction of degradation on ArF photoresist by C ₅ H ₇ plasma etching and its	Kohei Asano	Nagoya Univ.
P-18		Studies on Plasma Etching of Si ₃ N ₄ in Capacitively Coupled Plasma employing	Yudai Miyawaki	Nagoya Univ.
P-19		Etching Characteristics of MTJ Materials using CO/NH ₃ Gas Combination in Pulsed-bias ICP System	Jeon Min Hwan	Univ. of Sungkyunkwan
P-21	Plasma Generation, Diagnostics and Monitoring Technology	Calibrated optical emission spectra of CO ₂ and H ₂ /N ₂ plasmas in vacuum ultraviolet wavelength range	Koichi Sasaki	Hokkaido Univ.
P-22		N ₂ dissociation in a matrix ECR plasma source	C. Irimiea	Technical University of Denmark
P-23		Dielectric barrier discharge microplasma in small discharge gaps	Marius Blajan	Shizuoka Univ.
P-24		Characterization of an inductively coupled plasma microjet under low pressures	Q. Chen	The Univ. of Tokyo
P-25		Analytic model for an impedance analysis of a ferrite inductively coupled plasma	Daeho You	KAIST
P-26		Fault detection of rapid thermal annealing equipment by Principal Component Regression	Yoshiyuki Nakao	FUJITSU Semiconductor Limited
P-27		Development of cyclonic atmospheric pressure glow-discharge for a large-area organosilicon film deposition	Chun Huang	Yuan Ze Univ.
P-28		Plasma Characteristics of Inductively Coupled Plasma Using Dual Frequency Antenna	Kim Tae Hyung	Sungkyunkwan Univ.
P-29		Characterization of Steady-State Plume in Plasma Electron Ablation Method	T. Banno	Univ. of Tokyo
P-30		Ideal Low Electron Temperature Plasma Reactor	Rod Boswell	Australian National
P-31	Modeling and Simulation	Study of low pressure inductively coupled Ar/N ₂ plasmas: Effects of dc bias and gas flow rate	Lizhu Tong	Keisoku Engineering System Co., Ltd.
P-32		Bosch Process Simulations: From the Plasma to the Feature Scale	Sergio Lopez-Lopez	Quantemol Ltd
P-33		Molecular Dynamics Analysis of Surface Structure and Etch Products in Si/Cl and Si/Br Systems	N. Nakazaki	Kyoto University
P-41	CVD/Sputter Deposition	Material and precursor design for PECVD SiCH films to realize low-k cap layer in ULSI Cu-interconnects: porosity control and its analysis	Hideharu Shimizu	Univ. of Tokyo
P-42		Inductively Coupled Plasma-Assisted Mist CVD for Low Temperature and High Rate Deposition of ZnO Films	Kosuke Takenaka	Osaka Univ.
P-43		Sputter deposition of Epitaxial Zinc-Indium Oxynitride Films for Excitonic Transistors	N. Itagaki	Kyushu Univ.
P-44		N ₂ or H ₂ /isobutane supermagnetron plasma chemical vapor deposition of hydrogenated amorphous CN _x films for amorphous CN _x /H ₂ p-Si photovoltaic cell	Haruhisa Kinoshita	Shizuoka Univ.
P-45		Nucleation mechanism of self-organized vertical nano-graphenes grown using inductively coupled plasma enhanced chemical vapor deposition	R. Tsukada	Meijo University
P-46		Enhancing the Electron Field Emission Properties of Ultra-nanocrystalline Diamond Films by Growing on Textured Si Substrate	Wen-Ching Shih	Tatung Univ.
P-47		Thermal Stability of Hydrogenated and Hydrogen Free DLC Films by Elevated Heating	T. Kadoguchi	Toyohashi Univ. of Technology
P-48		The Effect of TiO ₂ and MgO Powder Spray on the Discharge Characteristics of an AC-	Sung-Suk Wi	Pusan National Univ.
P-51	Plasma Processes for 3D Device, FPD, Photovoltaic Devices	Performance enhancement of c-Si/organic heterojunction solar cells by using Si	Yuting Wang	Kyushu Univ.
P-52		Optimum process condition of Ti films deposition on porous TiO ₂ layer using RF magnetron sputtering for photovoltaic application	A. Chaoumead	Kyungshung Univ.
P-53		Layer Transfer and Simultaneous Crystallization of Amorphous Si Films with Mid-Air Structure Induced by Near-Infrared Semiconductor Diode Laser Irradiation and Its Application to Thin-Film Transistor Fabrication	K. Sakaike	Hiroshima Univ.
P-54		Fabrication of transparent CuCrO ₂ /Mg/ZnO p-n junctions prepared by RF sputtering on ITO glass substrate	Li-Fong Chen	Tatung Univ.
P-55		Fabrication of IndiumTin Oxide Thin Films by FTS System in Various Conditions	Kyung Hwan Kim	Gachon Univ.
P-56		Properties of GAZO/Ag/GAZO/Ag/GAZO transparent conductive multilayer film prepared by facing targets sputtering	Yu Sup Jung	Gachon Univ.
P-57		Properties of Ga-Al doped ZnO films prepared on the polymer substrate	Ki Hyun Kim	Gachon Univ.
P-58		Electrochromic properties of tungsten oxide films prepared by reactive sputtering	Min Hong Kim	Gachon Univ.
P-59		Luminescence characteristics of electrochemical cell using TiO ₂ layers prepared by dry and wet coating methods	S. H. Park	Kyungshung Univ.
P-60		Study of TSV Formation with ICP Parameter Control	Yu-Chen Hu	National Chiao Tung
P-61	Plasma Processes for Power device	A High Temperature Plasma Etching of GaN and Its Reaction Mechanism	Ryosuke Kometani	Nagoya Univ.
P-62		Atmospheric pressure microplasma treatment of GaN surface	Yuta Noma	Shizuoka Univ.
P-63		Damage Characteristics of p-GaN Surfaces Etched by Capacitively Coupled Radio Frequency Argon Plasmas	Retsuo Kawakami	The Univ. of Tokushima
P-64		In-situ Photoluminescence Measurements of GaN Films Exposed to Inductively-Coupled Plasmas	Keiji Nakamura	Chubu Univ.
P-71	Plasma Processes for Biological and Medical Application, MEMS	Temperature Controllable Multi-Gas Plasma Jet Source for Medical Applications	Toshihiro Takamatsu	Tokyo Institute of Technology
P-72		Growth promotion of Raphanus sativus L. and Oryza sativa using a combinatorial plasma irradiation method	Satoshi Kitazaki	Kyushu Univ.
P-73		Effect of Plasma Gas Temperature and Plasma Gas Species on Sterilization of E. coli	A. Kawate	Tokyo Institute of Technology
P-74		Plant growth regulation and redox reactions in plants induced by oxygen radical generated by air plasma	N. Hayashi	Kyushu Univ.
P-75		Plasma surface modification of carbon nanowalls for biosensor application	M. Nagashima	Meijo University
P-81	Atmospheric Pressure Plasma and Liquid Plasma	Rapid Thermal Annealing of SiC Wafer by Atmospheric Pressure Thermal Plasma Jet Irradiation	Ryuhei Ashihara	Hiroshima Univ.
P-82		Improvement of adhesion strength of epoxy resin/PTFE interface by atmospheric pressure plasma treatment of PTFE	Yasuhiro Hara	Univ. of Osaka
P-83		Atmospheric pressure plasma CVD of amorphous fluorocarbon films using hexafluorobenzene and argon	Chun Huang	Yuan Ze Univ.
P-84		Dynamic decomposition of CO ₂ by large flow atmospheric microwave plasma LAMP	S. Ikezawa	Chubu Univ.
P-85		Interfacial Analysis of Electroless Copper Thin Film on Fluorocarbon polymer Fabricated by Combination of Plasma Irradiation with Graft Copolymerization	Kento Ooka	Univ. of Osaka
P-86		Investigation of NO _x reduction by low temperature oxidation and direct plasma treatment	E. Stamate	Technical University of Denmark